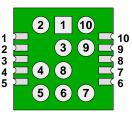


Surface mount Foot Map (top View)



NOT TO SCALE

1

Substrate: 0.0625"±0.007" per IPC 4101/21/26/83/98, Td>=345C 1/2 oz. Cu clad. RoHS finish



Pins: Material- Brass Alloy 360 1/2 hard; finish- $10\mu^{\text{\tiny II}}$ Au over $50\mu^{\text{\tiny II}}$ Ni (min.).



Pins: shell material- Brass Alloy 360 1/2 hard; finish-10 μ " Au over 50 μ " Ni (min.). Contact material- BeCu; finish 10 μ " Au over 100 μ " Ni (min.)



Test points: material- Phosphor Bronze; plating- Sn over $50\mu^{\shortparallel}$ Ni. Gold flash on contact end.

Description: Carrier Adaptor, SOIC

10 position ZIF socket with test points to 10 position surface mount foot, 0.5mm pitch (leadless). Two piece assembly has gold plated pluggable interface between socket and foot assemblies. Pin mapping is 1:1

Tolerances: diameters ±0.03mm [±0.001"], PCB perimeters ±0.13mm [±0.005"], PCB thicknesses ±0.18mm [±0.007"], pitches (from true position) ±0.08mm [±0.003"], all other tolerances ±0.13mm [±0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

